

## CHO-BOND® 584-29 SYRINGE-PAK™

### Silver Filled Conductive Epoxy and Hardener in Easy to Use Packaging

#### DESCRIPTION

Chomerics CHO-BOND® 584-29 is a two-component, highly conductive adhesive system that combines the strong adhesive characteristics of epoxy with the superior conductivity of pure silver. In addition to being available in bulk form, the material is now offered in the convenient pre-measured SYRINGE-PAK™ for rapid application. This new syringe system simplifies the mixing of resin and hardening components, and improves dispensing accuracy and efficiency. The result is less compound waste and lower applied cost.

CHO-BOND 584-29 conductive adhesive has a low viscosity allowing easier application through fine gauge needles. With its silver filler, the compound provides a low volume resistivity of 0.002 ohm-cm when used as a highly conductive pathway in microelectronics, circuit repair, EMI shielding systems, ground paths, and other applications. The adhesive cures at room temperature in 24 hours.



#### FEATURES

- Easy and efficient application system
- Pure silver filler. Superior conductivity.
- 100% solids, no VOC's.
- Room temperature cure in 24 hours

#### TYPICAL PROPERTIES

Property	Typical values 584-29	Method
Volume Resistivity	0.002 ohm-cm	Chomerics 95-40-5101 and 95-40-5102
Specific Gravity	2.2	ASTM D792
Filler	Ag	--
Shelf Life @ RT, (mos.)	9	--
Mix Ratio (by wgt.)	100:6.3	--
Lap Shear Min. (psi)	1200	ASTM D1002
Working Life	30 mins.	--
Elevated Temp. Cure Cycle Time @°F (°C)	15 min. @ 235 (113)	--

#### PART NUMBER INFORMATION

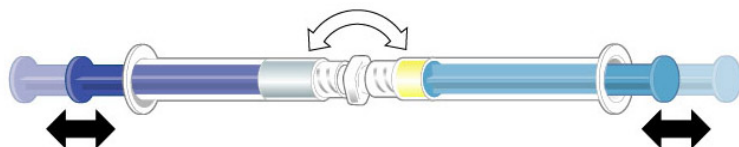
3 gram Kit (resin & hardener)	10 Kit Package	50-30-584-0029
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## APPLICATION

The new dispense system for CHO-BOND 584-29 adhesive features a pair of syringes, one containing a hardener and one with the conductive resin, separated by a connector. The compounds are quickly mixed between the syringes, and one syringe is used to apply the mixed conductive adhesive. A needle can be attached to the dispensing syringe to produce finer beads, or to deposit points of adhesive in hard to reach places. Prior to application, ensure that bonding surfaces are clean and free of any greases, oils or contaminants.

### STEP 1

Remove the caps from the 584-29 epoxy (dark blue) and hardener (light blue) syringes. Insert the coupler into the threads of one of the syringes and turn in a clockwise motion. Repeat this step for the second syringe.

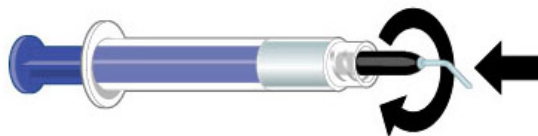


### STEP 2

Ensure both syringes are secured tightly with the coupler. Gently mix the epoxy and hardener by filling each syringe 6-8 times.

### STEP 3

Remove the empty syringe and the coupler. Insert the dispensing needle and turn clockwise. You are now ready to dispense the 584-29 compound.



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